



Material Content Data Sheet



Sales Product Name		TLE7185-1E		Issued		24. January 2018		
MA#		MA001185972						
Package		PG-DSO-36-38		Weight*		608.64 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.970	1.47	1.47	14738	14738
leadframe	inorganic material	phosphorus	7723-14-0	0.057	0.01		93	
	non noble metal	zinc	7440-66-6	0.227	0.04		373	
	non noble metal	iron	7439-89-6	4.546	0.75		7468	
wire	non noble metal	copper	7440-50-8	184.568	30.32	31.12	303245	311179
	noble metal	gold	7440-57-5	1.294	0.21	0.21	2126	2126
	encapsulation	organic material	carbon black	1333-86-4	0.800	0.13		1314
encapsulation	plastics	epoxy resin	-	36.787	6.04		60441	
	inorganic material	silicondioxide	60676-86-0	362.272	59.53	65.70	595211	656966
leadfinish	non noble metal	tin	7440-31-5	5.440	0.89	0.89	8938	8938
plating	noble metal	silver	7440-22-4	0.791	0.13	0.13	1300	1300
glue	plastics	epoxy resin	-	0.723	0.12		1188	
	noble metal	silver	7440-22-4	2.170	0.36	0.48	3565	4753
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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